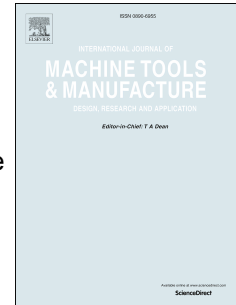


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## **Modeling and Simulation of the distribution of undeformed chip thicknesses in surface grinding**

Yuzhou Zhang<sup>a,b</sup>, Congfu Fang<sup>a</sup>, Guoqin Huang<sup>a</sup>, Xipeng Xu<sup>a,\*</sup>

<sup>a</sup> Institute of Manufacturing Engineering, Huaqiao University, Xiamen, 361021, Fujian Province, PR China

<sup>b</sup> School of Mechanical and Energy Engineering, Jimei University, Xiamen, 361021, Fujian Province, PR China

\* Corresponding Author

E-mail: [xuxipengvip@163.com](mailto:xuxipengvip@163.com); [xpxu@hqu.edu.cn](mailto:xpxu@hqu.edu.cn);

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### **Declaration of Interest**

The authors have no conflicts of interest to declare

### **Role of the Funding Source**

### **Vitae**

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